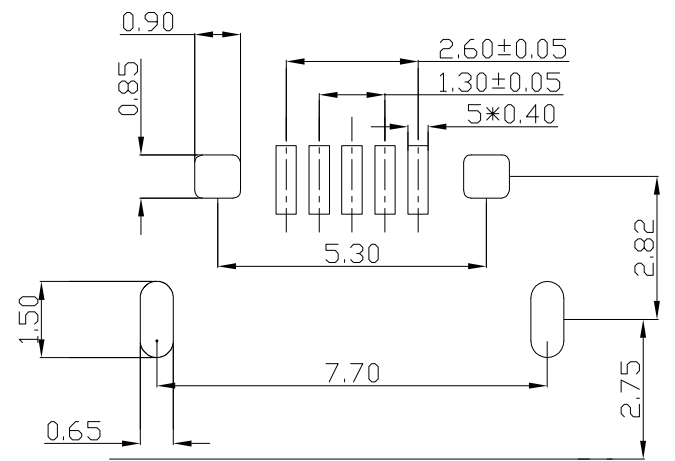
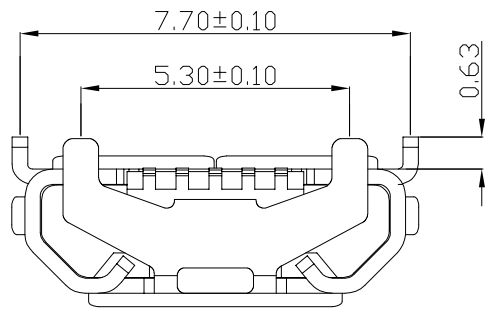
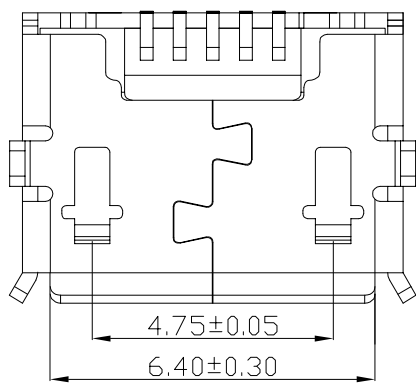
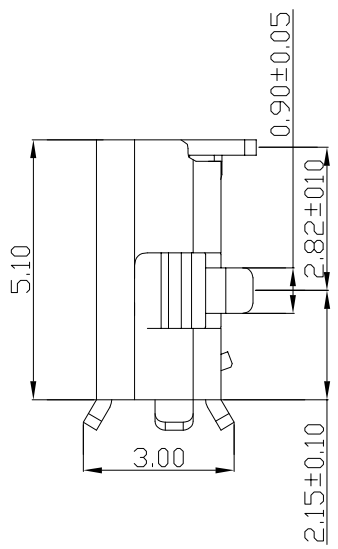
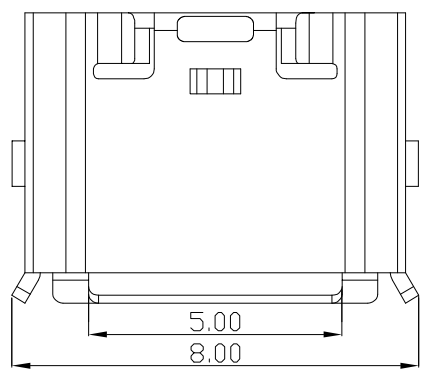


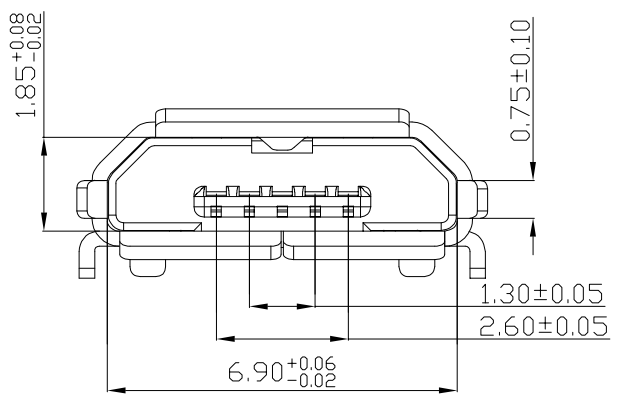
REV.	ECN.NO.	APPD.
A0	/	/



PCB LAY UT



Note:  
 1.Material:  
 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0  
 1.2 Contact: copper alloy,t=0.15mm  
 1.3 Shell: copper alloy&SUS  
 2.Specification:  
 2.1 Current rating: 1 A Max.  
 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.  
 2.3 Contact resistance: 30 mΩ Max.  
 2.4 Insulation resistance: 100 MΩ Min.  
 2.5 Total mating force: 3.57 Kgf Max.  
 2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extraction cycles  
 2.7 Temperature range: -30°C~80°C



- U442-621X-XXX0X8
- 1: 铁壳镀镍
  - 5: 铜壳镀镍
  - 4: 铁壳镀金
  - 6: 铜壳镀雾锡
  - 8: 铜壳镀金
  - 1: 半金1u"
  - 3: 半金3u"
  - G: 半金G/Fu"
  - 1: 吸塑盒
  - 3: 冷封载带
  - 8: 热封载带
  - 1: 黑色
  - 2: 白色
  - 3: 米黄色
  - 1: PA66
  - 2: PBT
  - 6: LCP

TOLERANCE UNLESS OTHERWISE SPECIFIED	
.XXX ±0.10	.X' ±3'
.XX ±0.20	.XX' ±2'
.X ±0.30	

**FLW** 深圳市华联威电子科技有限公司  
 HUA LIAN WEI TECHNOLOGY ELECTRONICS CO;LTD.

APPROVED		PART NAME:	MICRO 5P/F 牛角反向			
CHECKED		PART No:	U442-6216-X61038		C	
DRAWN	weihong	PROJECTION:	UNIT:	SCALE	SHEET	REV.
DATE	2021.06.03		mm	1:1	10F1	A0